AMENDMENT TRANSMITTAL LETTER (Large Entity)

Docket No. YUSO-131

Applicant(s): Hsieh et al .

Group Art Unit: 2818

Examiner: David Vu

Application No.: 10/052,989

Filing Date: November 9, 2001

Invention: Formation of electroplate solder on an organic circuit board for flip chip joints and board to board

solder joints

COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS AMENDED

	Claims Rei After Amer			hest # <u>Paid For</u>	Number <u>Claims Pr</u>	Extra resent Rate	<u>Fee</u>
Total Claims	10	-	20	=	0	X \$50	0.00
Indep. Claims	1	-	3	=	0	X \$200	0.00
						TOTAL:	\$ -0-

☑ ^	No additional fee is required for a	amendment.
	A check in the amount of	to cover the filing fee is enclosed.

Date:

Raymond Sun Reg. No. 35,699

CERTIFICATE OF MAILING

I hereby certify that the above-identified document is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on:





IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Hsieh et al.) Art Unit: 2818)
Serial No.: 10/052,989) Examiner: David Vu)
Filing Date: November 9, 2001)
For: Formation of Electroplate Solder on an Organic Circuit Board for Flip Chip Joints and Board to Board Solder Joints))))

Mail Stop After Final Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT TO FINAL OFFICE ACTION DATED MARCH 3, 2006

In response to the Final Office Action dated March 3, 2006, please enter and consider the following amendments and remarks: